

959T

Low-Solids No-Clean Liquid Flux

Product Description

Kester 959T is a no-clean, non-corrosive, liquid flux that is designed for the wave soldering of conventional and surface mount circuit board assemblies. Kester 959T was developed to minimize the formation of micro-solderballs during wave soldering operations. This flux contains a small percentage of rosin (0.5%), which improves solderability, heat stability and surface insulation resistance. Kester 959T offers the best wetting and the shiniest solder joints of any no-clean, solvent-based chemistry. Kester 959T leaves evenly distributed residues for the best cosmetic appearance.

Performance Characteristics:

- Minimize micro-solderballs
- Extremely shiny joints
- No streaky, white residues
- Improves soldering performance
- Eliminates the need and expense of cleaning
- Classified as ORL0 per J-STD-004
- Compliant to Bellcore GR-78

RoHS Compliance

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances.

Physical Properties

Specific Gravity: 0.794 ± 0.005

Antoine Paar DMA 35 @ 25°C

Percent Solids (typical): 2.9

Tested to J-STD-004, IPC-TM-650, Method 2.3.34

Acid Number: 21.0 ± 1.0 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

Flash Point: 18°C (64°F)

Reliability Properties

Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

SIR, IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	959T PD	959T PU
Day 1	7.9 × 10 ⁹ Ω	1.6 × 10 ⁹ Ω	1.7 × 10 ⁹ Ω
Day 4	8.4 × 10 ⁹ Ω	1.9 × 10 ⁹ Ω	5.3 × 10 ⁹ Ω
Day 7	7.4 × 10 ⁹ Ω	1.9 × 10 ⁹ Ω	2.8 × 10 ⁹ Ω

Application Notes

Flux Application:

Kester 959T can be applied to circuit boards by a spray, foam or dip process. Flux deposition should be 120-240 μg of solids/ cm^2 (750-1500 μg of solids/ in^2). An air knife after the flux tank is recommended to remove excess flux from the circuit board and prevent dripping on the preheater surface.

Process Considerations:

The optimum preheat temperature for most circuit assemblies is 90-105°C (194-221°F) as measured on the top or component side of the printed circuit board. Dwell time in the wave is typically 2-4 seconds. The wave soldering speed should be adjusted to accomplish proper preheating and evaporate excess solvent, which could cause spattering. For best results, speeds of 1.1-1.8 m/min (3½-6 ft/min) are used. The surface tension has been adjusted to help the flux form a thin film on the board surface allowing rapid solvent evaporation.

Flux Control:

Acid number is normally the most reliable method to control the flux concentration of low solids, no clean fluxes. To check concentration, a simple acid-base titration should be used. PS-22 Test Kit and procedure are available from Kester. Control of the flux in the foam flux tank during use is necessary for assurance of consistent flux distribution on the circuit boards. The complex nature of the solvent system for the flux makes it imperative that Kester 4662 Thinner be used to replace evaporative losses. When excessive debris from circuit boards, such as board fibers and from the air line build up in the flux tank, these particulates will re-deposit on the circuit boards which may create a build up of residues on probe test pins. It is, therefore, necessary to clean the tank and then replenish it with fresh flux when excessive debris accumulates in the flux tank.

Cleaning:

Kester 959T flux residues are non-conductive, non-corrosive and do not require removal in most applications.

Storage and Shelf Life:

Kester 959T is flammable. Store away from sources of ignition. Shelf life is 3 years from date of manufacture when handled properly and held at 10-25°C (50-77°F).

Health & Safety:

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

World Headquarters: 800 W. Thorndale Avenue, Itasca, Illinois, 60143 USA

Phone: (+1) 630-616-4000 • **Email:** customerservice@kester.com • **Website:** www.kester.com

Asia Pacific Headquarters

500 Chai Chee Lane
Singapore 469024
(+65) 6449-1133
customerservice@kester.com.sg

European Headquarters

Zum Plom 5
08541 Neuensalz
Germany
(+49) 3741 4233-0
customerservice@kester-eu.com

Japanese Headquarters

20-11 Yokokawa 2-Chome
Sumida-Ku
Tokyo 130-0003 Japan
(+81) 3-3624-5351
jpsales@kester.com.sg
